

Layered board for copper@ printed circuit boards - including unit layers composed of glass non-woven fabric impregnated with polyepoxy resin and inorganic filler e.g. graphite, etc., carbon@ PCB

Patent Assignee: SUMITOMO BAKELITE CO LTD (SUMB )

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 7176843	A	19950714	JP 93322388	A	19931221	199537 B

Priority Applications (No Type Date): JP 93322388 A 19931221

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 7176843	A	4	H05K-001/03	

Abstract (Basic): JP 7176843 A

In a layered board for a printed circuit produced by preparing unit resin impregnation layer each composed of a glass non-woven fabric impregnated with epoxy resin and inorganic filler, then layering the unit resin impregnation layers with application of heat and pressure, the content of the inorganic filler is 10-200 pts.wt. - 100 pts.wt. of the resin, and the ratio of the length to the thickness of the filler is in range of 5.0-200.

USE/ADVANTAGE - Suitable for a copper-layered printed circuit board. The layered board has good dimensional accuracy, drill workability and punching workability.

The epoxy resin is e.g. brominated epoxy resin, non-brominated epoxy resin, bisphenol A type epoxy resin or novolak type epoxy resin etc.. The inorganic filler e.g. consists of mica, graphite or wollastonite, etc..

Dwg.0/0

Title Terms: LAYER; BOARD; COPPER; PRINT; CIRCUIT; BOARD; UNIT; LAYER; COMPOSE; GLASS; NON; WOVEN; FABRIC; IMPREGNATE; POLYEPOXIDE; RESIN; INORGANIC; FILL; GRAPHITE; CARBON; PCB

Derwent Class: A21; A85; L03; P73; V04

International Patent Class (Main): H05K-001/03

International Patent Class (Additional): B32B-015/08; B32B-017/04; B32B-027/38; C08J-005/24; H05K-003/00

File Segment: CPI; EPI; EngPI

?